



Material Content Data Sheet



Sales Product Name				AIHD06N60R		Issued		22. January 2018	
MA#				MA001372490					
Package				PG-TO252-3-313		Weight*		316.92 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.924	0.29	0.29	2916	2916	
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139		
	non noble metal	iron	7439-89-6	0.147	0.05		465		
	non noble metal	copper	7440-50-8	147.096	46.41	46.47	464143	464747	
	non noble metal	aluminium	7429-90-5	0.527	0.17	0.17	1662	1662	
wire	non noble metal	aluminium	7429-90-5	0.527	0.17	0.17	1662	1662	
encapsulation	organic material	carbon black	1333-86-4	1.427	0.45		4504		
	plastics	epoxy resin	-	24.977	7.88		78812		
	inorganic material	silicondioxide	60676-86-0	116.323	36.70	45.03	367040	450356	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11801	11801	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4482	4493	
solder	non noble metal	tin	7440-31-5	0.022	0.01		69		
	noble metal	silver	7440-22-4	0.027	0.01		86		
	non noble metal	lead	7439-92-1	1.039	0.33	0.35	3279	3434	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		61		
	non noble metal	copper	7440-50-8	19.177	6.05	6.06	60512	60591	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com